



Material Content Data Sheet



Sales Product Name		BFP 520F H6327		Issued		19. July 2018		
MA#		MA001351310						
Package		PG-TSFP-4-1		Weight*		1.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.03		269	
	noble metal	gold	7440-57-5	0.002	0.10		1041	
	inorganic material	silicon	7440-21-3	0.014	0.77	0.90	7715	9025
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		395	
	non noble metal	chromium	7440-47-3	0.002	0.12		1184	
	non noble metal	copper	7440-50-8	0.734	39.30	39.47	393028	394686
wire	noble metal	gold	7440-57-5	0.007	0.35	0.35	3543	3543
encapsulation	organic material	carbon black	1333-86-4	0.010	0.52		5180	
	plastics	epoxy resin	-	0.208	11.14		111376	
	inorganic material	silicondioxide	60676-86-0	0.750	40.15	51.81	401472	518028
leadfinish	non noble metal	tin	7440-31-5	0.050	2.65	2.65	26527	26527
plating	noble metal	silver	7440-22-4	0.090	4.82	4.82	48191	48191
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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